

SOT947-1

plastic, ball grid array package; 564 balls; body 40 x 40 x 1.75 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA564
Package type industry code	BGA564
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	31-5-2006

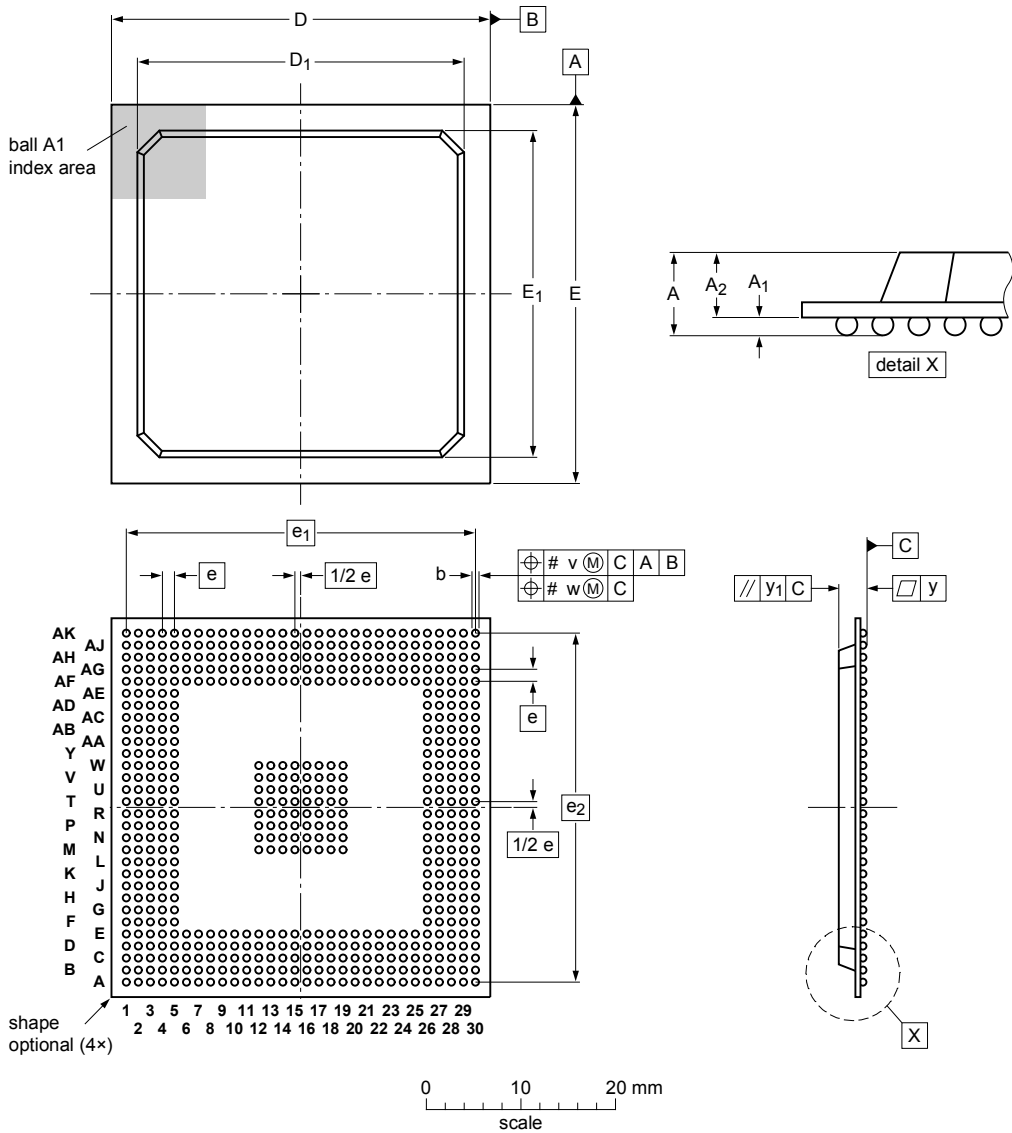
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	39.8	-	40	40.2	mm
E	package width	39.8	-	40	40.2	mm
A	seated height	[tbd]	-	2.55	2.55	mm
A ₂	package height	1.6	-	1.75	1.85	mm
n ₂	actual quantity of termination	-	-	564	-	



2. Package outline

BGA564: plastic ball grid array package; 564 balls; body 40 x 40 x 1.75 mm SOT947-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	D ₁	E	E ₁	e	e ₁	e ₂	v	w	y	y ₁
mm	2.55	0.7 0.5	1.85 1.60	0.9 0.6	40.2 39.8	35.25 34.25	40.2 39.8	35.25 34.25	1.27	36.83	36.83	0.3	0.15	0.2	0.35

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT947-1		MS-034				06-04-14 06-05-31

Fig. 1. Package outline BGA564 (SOT947-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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